ELECTRONIC COATINGS HAVING LOW DIELECTRIC CONSTANT

ABSTRACT

This invention is a method for producing insoluble coatings having a dielectric constant (Dk) of 2.5 to 2.8 on electronic substrates. The method comprises applying a composition comprising hydrogen silsesquioxane resin onto a substrate to form a film on the substrate; and heating the substrate at a temperature of 200°C. to 550°C. wherein the substrate is heated at a rate and for a time sufficient to produce an insoluble coating having a dielectric constant of 2.5 to 2.8.